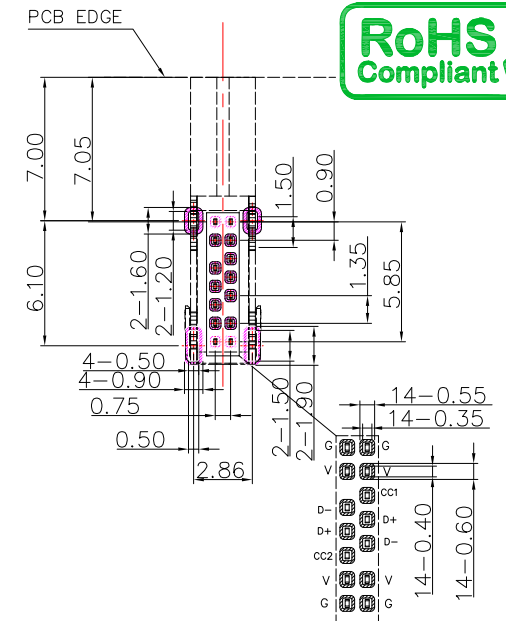
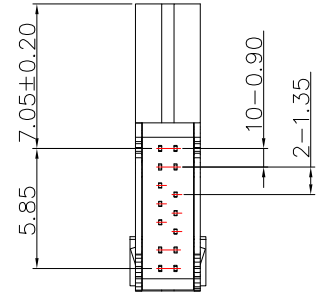
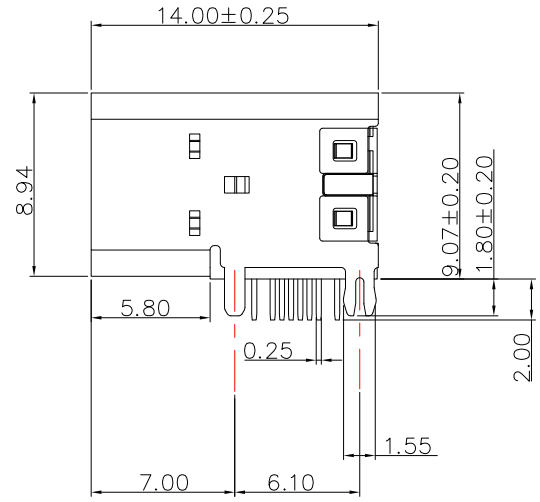
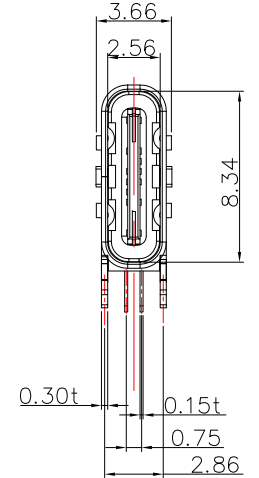
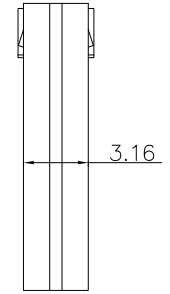




SBC-140P-20x-S242

鍍層厚度:

Blank : 1u"
2 : 15u"
3 : 30u"



RECOMMENDED P.C.B. LAYOUT

SPECIFICATIONS

- Electrical:**
1. Dielectric Withstand Voltage: 100V AC
  2. Contact Resistance: 40 mΩ Max
  3. Insulation Resistance: 100 MΩ Min
- Mechanical:**
1. Connector Mate and Unmate Force
    - 1.1 Mate force: 5~20 N
    - 1.2 Unmate force: 8~20 N
- Material:**
1. Housing: High-Temp
  2. Contact: Copper Alloy
  3. Shell: SUS
- Finish:**
1. Contact: Plated Gold in Mating Area ;  
Tin Plated on Solder Balls ;  
Nickel under plated overall
  2. Shell: Nickel under Plated surface layer

**CONTACT** 建倚科技股份有限公司  
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED:	Up to 5 ±0.2	3RD. ANGEL'S	UNITS	MM
	Above 5 ~ 15 ±0.3			
	Above 15 ~ 30 ±0.4			
	Above 30 ~ 50 ±0.5			
	Angle ±0.3°			

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	09/06/19		MODLE	USB 3.1 側插母座 14 PIN
CHECKED BY:	DATE	FINISH	DWG NO.	SBC-140P-20x-S242
Jacky Chen	09/06/19		PART NO.	SBC-140P-20x-S242
APPROVED BY:	DATE	SCALE	1 of 1	
Tony Kao	09/06/19	SHEET NO.		
			SIZE	A4
			VER	R1

1	新增PCB LAYOUT尺寸	Jack	090619
ITEM NO.	DESCRIPTION	DRAWN	DATE